

ABSTRACT OF THE DISCLOSURE

5 A freely positionable placement head removes presented flip chips from a wafer with the connection side of said chips being directed upward. The placement head has a turning device, in which, by the time they are placed onto a substrate to be provided with placed components, the flip chips are turned in such a way that they can be placed with their connection side onto the substrate. This makes it possible to dispense with a complex turning device assigned to the wafer.